

### 描述 / Descriptions

SOP-8 塑封封装 P 沟道场效应管。

P-Channel Enhancement Mode Field Effect Transistor in a SOP-8 Plastic Package.

### 特征 / Features

$V_{DS} (V) = -40V$

$I_D = -10 A (V_{GS} = \pm 20V)$

$R_{DS(ON)} < 15m\Omega (V_{GS} = -10V)$

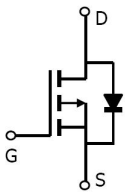
无卤产品。HF Product.

### 用途 / Applications

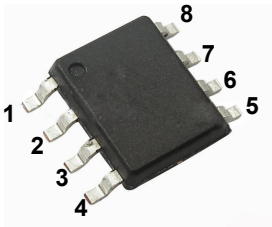
用于电源管理，便携式设备和电池供电系统。

Power Management in Notebook computer, Portable Equipment and Battery powered systems.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN 1 : S    PIN 2 : S    PIN 3 : S    PIN 4 : G

PIN 5 : D    PIN 6 : D    PIN 7 : D    PIN 8 : D

### 印章代码 / Marking

见印章说明 See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	$V_{DSS}$	-40	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$I_D (T_a=25^\circ\text{C})$	-10	A
Continuous Drain Current	$I_D (T_a=70^\circ\text{C})$	-8	A
Power Dissipation for Single Operation	$P_D (T_a=25^\circ\text{C})$	1.7	W
Power Dissipation for Single Operation	$P_D (T_a=70^\circ\text{C})$	1.1	W
Maximum Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 ~ 150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA} (t \leq 10\text{s})$	40	$^\circ\text{C}/\text{W}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	75	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Lead	$R_{\theta JL}$	24	$^\circ\text{C}/\text{W}$

## 电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=-250\mu A$ $V_{GS}=0V$	-40			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-40V$ $V_{GS}=0V$			-1.0	$\mu A$
		$V_{DS}=-40V$ $V_{GS}=0V$ $T_J=55^\circ C$			-5.0	
Gate-Body leakage current	$I_{GSS}$	$V_{DS}=0V$ $V_{GS}=\pm 20V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1.2	-1.6	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V$ $I_D=-10A$		13.1	15	m $\Omega$
		$V_{GS}=-4.5V$ $I_D=-7A$		18	21	
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V$ $I_D=-10A$		9.5		S
Diode Forward Voltage	$V_{SD}$	$I_S=-1A$ $V_{GS}=0V$		-0.8	-1.0	V
Total Gate Charge	$Q_g(10V)$	$V_{GS}=-10V$ $V_{DS}=-20V$ $I_D=-10A$		42	55	nC
Total Gate Charge	$Q_g(4.5V)$			18.6		
Gate-Source Charge	$Q_{gs}$			7		
Gate-Drain Charge	$Q_{gd}$			8.6		
Gate Resistance	$R_g$	$V_{GS}=0V$ $f=1MHz$	$V_{DS}=0V$		8.5	$\Omega$
Input Capacitance	$C_{iss}$	$V_{GS}=0V$ $f=1MHz$	$V_{DS}=-25V$		3300	pF
Output Capacitance	$C_{oss}$				135	
Reverse Transfer Capacitance	$C_{rss}$				177	
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V$ $V_{DS}=-20V$ $R_L=2\Omega$ $R_{GEN}=3\Omega$		9.4		ns
Turn-on Rise Time	$t_r$			20		
Turn-off Delay Time	$t_{d(OFF)}$			55		
Turn-off Fall Time	$t_f$			30		

电参数曲线图 / Electrical Characteristic Curve

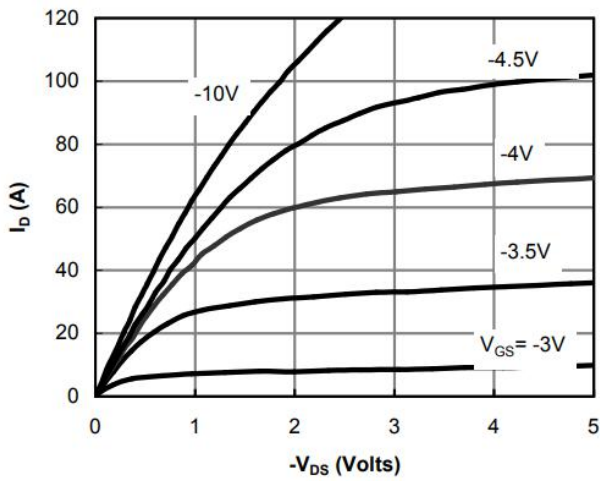


Figure 1: On-Region Characteristics

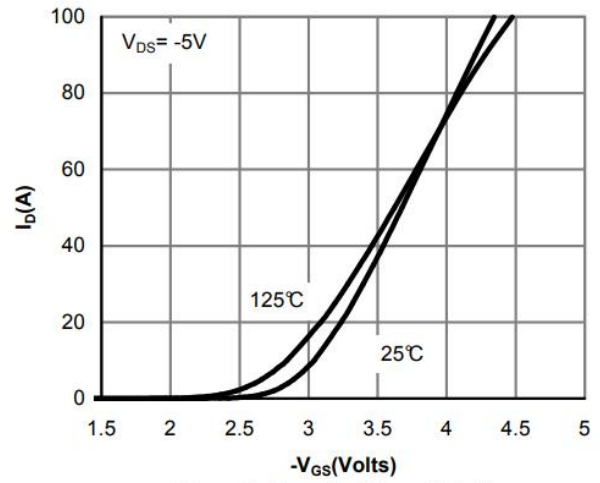


Figure 2: Transfer Characteristics

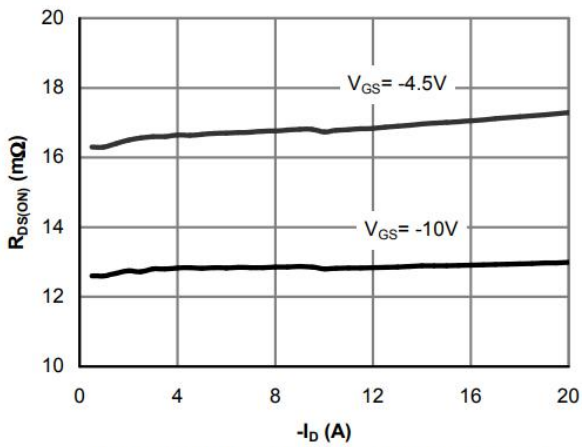


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

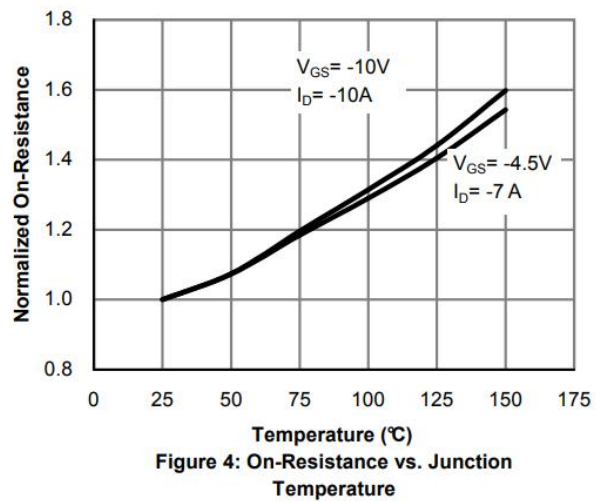


Figure 4: On-Resistance vs. Junction Temperature

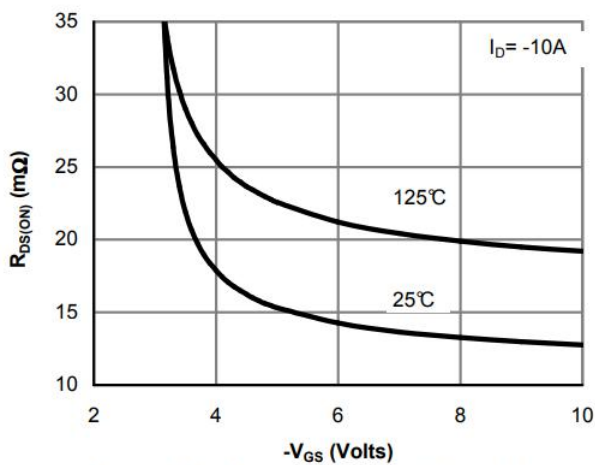


Figure 5: On-Resistance vs. Gate-Source Voltage

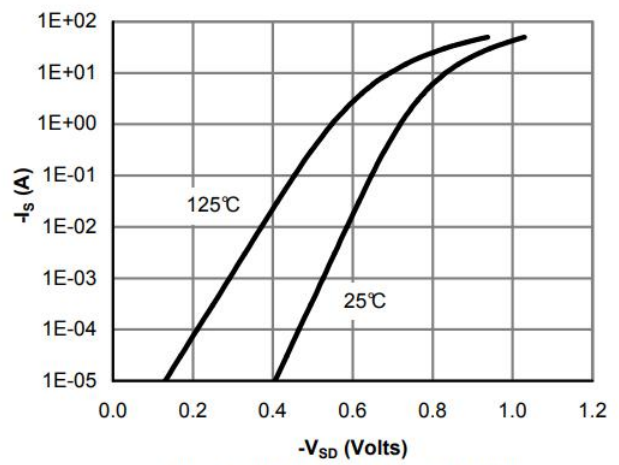


Figure 6: Body-Diode Characteristics

电参数曲线图 / Electrical Characteristic Curve

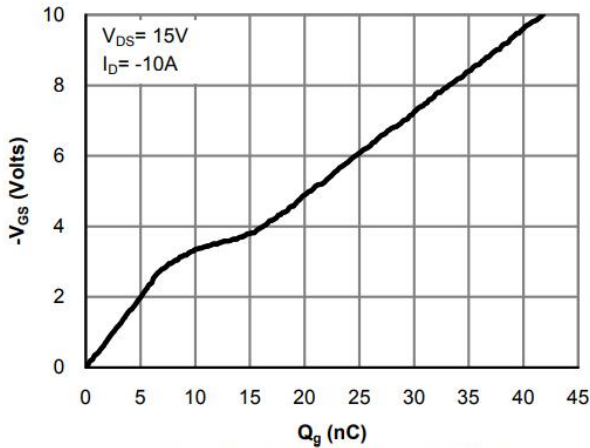


Figure 7: Gate-Charge Characteristics

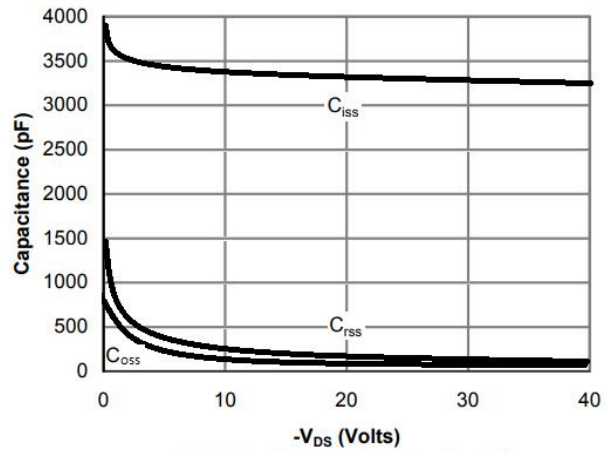


Figure 8: Capacitance Characteristics

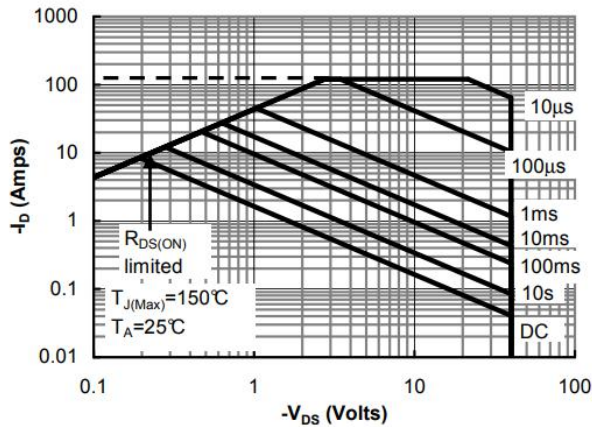


Figure 9: Maximum Forward Biased Safe Operating Area

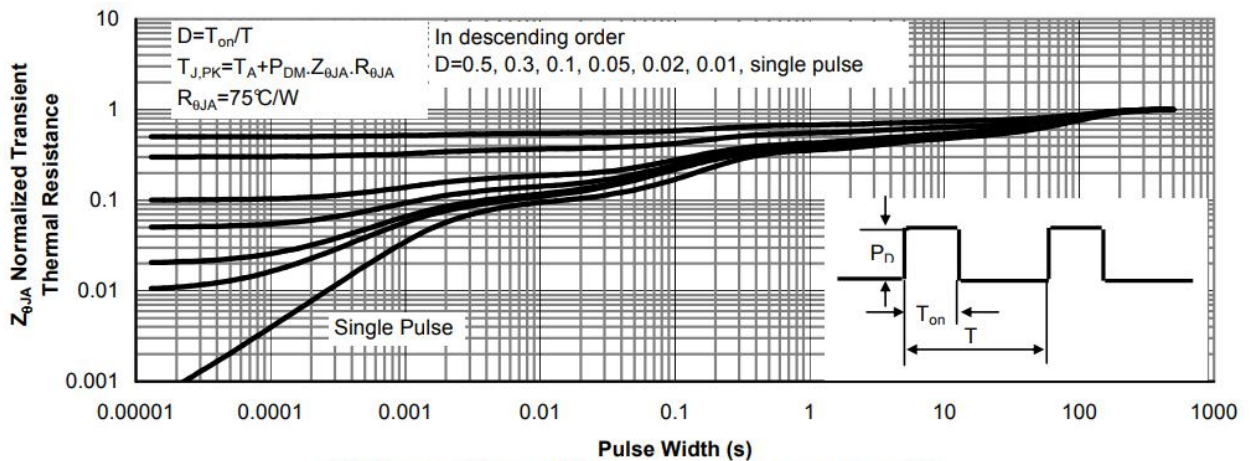
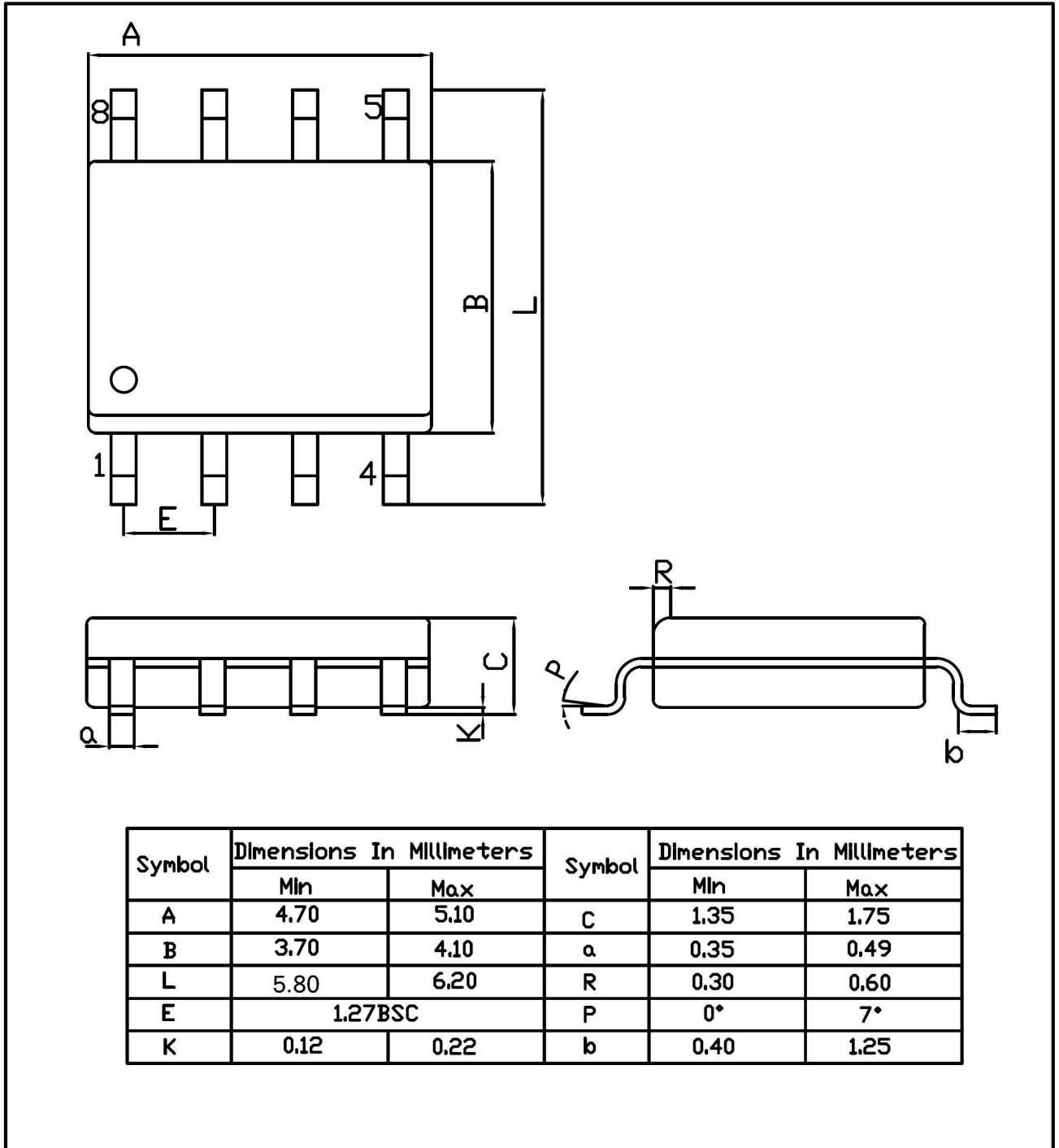


Figure 10: Normalized Maximum Transient Thermal Impedance

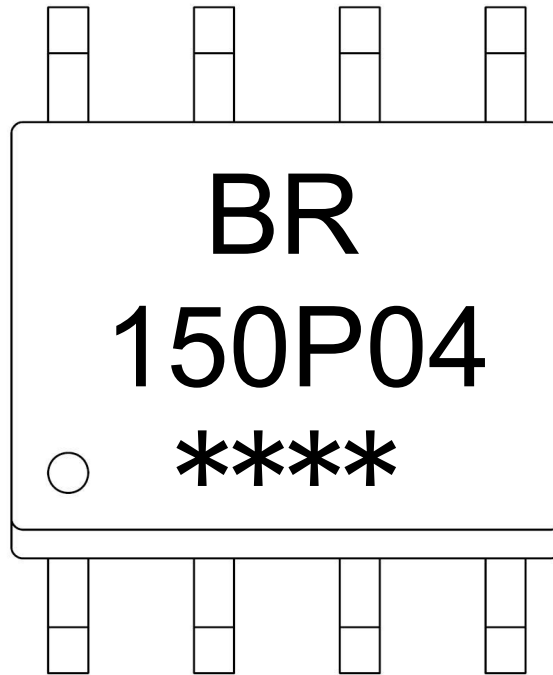
外形尺寸图 / Package Dimensions

SOP-8

Unit:mm



印章说明 / Marking Instructions



说明：

BR： 为公司代码

150P04： 为型号代码

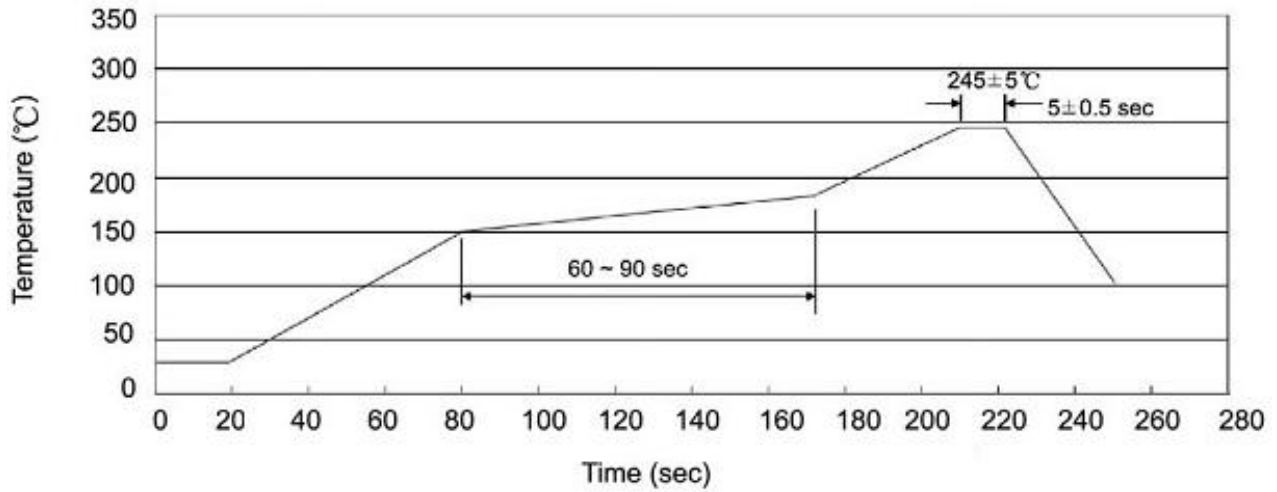
\*\*\*\*： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code.

150P04: Product Type

\*\*\*\*: Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" × 12	360×360×50	380×335×366

**使用说明 / Notices**